



SESSION 4

Foundries & IDM

Chair: **Bertrand Parvais**, imec



16:00 - 16:20

Jeffrey Wang - Advanced Micro Semiconductors

GaN Enabling High Efficiency for Power Conversion



16:20 - 16:40

Greg U'Ren - UMS

RFFE challenges for 5G BST



16:40 - 17:00

David Danzilio - Win Semiconductors

Best-Value Technologies for High Performance Front-Ends



17:00 - 17:20

Andreia Cathelin - STMicroelectronics

New Shapes in Perspective for Future RF/mmW Integrated Technology



17:20 - 17:40

Han Wui Then - Intel

GaN and Moore's law



17:40 - 17:50

Lou Hermans - Flanders Semiconductors

Flanders Semiconductors: Building a Semiconductor Ecosystem In and Around Flanders



17:50 - 18:00

Marianne Renoz - Incize

Closing Remarks

18:00 - 19:00

Networking Cocktail

19:00

DINNER



PROGRAM OF THE DAY

APRIL 4, 2025

OUR SPONSORS



The RF Workshop



SESSION 1

Market Insights
Chair: **Andreia Cathelin**, STMicroelectronics



8:50 - 9:00
Mostafa Emam - Incize
Opening Remarks



9:00 - 9:20
Laith Altimime - SEMI
AI Catalyst for Europe's
Competitiveness



9:20 - 9:40
Thomas Piliszczuk - imec
Advancing Connected Computing
- RF for Edge A



9:40 - 10:00
Cédric Malaquin - TechInsights
Compound Semiconductors and their
integration in RF systems



10:00 - 10:20
Cyril Buey - Yole Group
Overview of the RF Industry

10:20 - 10:40

COFFEE BREAK



SESSION 2

Substrates & Research
Chair: **Morin Dehan**, Incize



10:40 - 11:00
Jean-Marc Le Meil - Soitec
Innovative Substrate Engineering: Paving the
Way for Intelligent, Sustainable Communications



11:00 - 11:20
Atte Haapalinna - Okmetic
Advancing 5G & 6G with Enhanced Silicon Wafers



11:20 - 11:40
Jean-Pierre Raskin - UCLouvain
High-Resistivity FD-SOI Platform for
Radio Frequency Modules



11:40 - 12:00
Nadine Collaert - imec
GaN-Si for UE: The GaAs killer or
just another hype?



12:00 - 12:20
Martin Gallezot - CEA-Leti
How 3D integration can help towards 6G?



12:20 - 12:40
Madhavan Esayanur - MEMC-GlobalWafers
Engineering the Future of RF: Enabling
Performance Through Wafer Advancements

12:40 - 14:00

LUNCH



SESSION 3

Fabless
Chair: **Bich-Yen Nguyen**, Soitec



14:00 - 14:20
Manish Shah - TagoreTech
Advancing High Power RF Fronted SWaP with
GaN Technology



14:20 - 14:40
Ravi Vedula - Qualcomm
RFFE Technologies – Current Trends and Future
Challenges



14:40 - 15:00
Wayne Ni - CanaanTek
The Latest Challenges of RFSOI & SAW Filter
Designs for Miniature 5G Module Chip



15:00 - 15:20
Robert Mears - Atomera
Extending the Performance of RFSOI Devices
Through Oxygen Inserted (OI) Epitaxy



15:20 - 15:40
Joren Vaes - Sofics
Why ESD Co-Design is Key to Unlocking
Performance

15:40 - 16:00

COFFEE BREAK